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## BIB DATA SHEET

CONFIRMATION NO. 1863

SERIAL NUMBER	FILING or 371(c) DATE	CLASS	GROUP ART UNIT	ATTORNEY DOCKET NO.		
10/765,931	01/29/2004 RULE	<del>228</del> 438	2823	Q79041		
<b>APPLICANTS</b> Youichi Kukimoto, Kakogawa-shi, JAPAN; Hitoshi Sakurai, Kakogawa-shi, JAPAN; Seishi Kumamoto, Kakogawa-shi, JAPAN; Kenshu Oyama, Kakogawa-shi, JAPAN; <b>** CONTINUING DATA *****</b> None /KN/ <b>** FOREIGN APPLICATIONS *****</b> Yes /KN/ JAPAN 2003-110125 04/15/2003 <b>** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **</b> 06/12/2004						
Foreign Priority claimed 35 USC 119(a-d) conditions met Verified and Acknowledged	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No /KHIEM D NGUYEN/ Examiner's Signature	<input type="checkbox"/> Met after Allowance /KN/ Initials	STATE OR COUNTRY JAPAN	SHEETS DRAWINGS 2	TOTAL CLAIMS 15 <del>7</del>	INDEPENDENT CLAIMS 3 <del>2</del>
<b>ADDRESS</b> SUGHRUE MION, PLLC 2100 PENNSYLVANIA AVENUE, N.W. SUITE 800 WASHINGTON, DC 20037 UNITED STATES						
<b>TITLE</b> Solder deposition method and solder bump forming method						
<b>FILING FEE RECEIVED</b> 1640	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:			<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		